



Material Content Data Sheet



Sales Product Name		BGT 70 E6327		Issued		22. January 2018		
MA#		MA001269776						
Package		PG-WFWLB-119-1		Weight*		52.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.210	27.22	27.22	272250	272250
dielectric layer	non noble metal	copper	7440-50-8	0.767	1.47		14686	
	plastics	phenolresin	-	0.796	1.53	3.00	15257	29943
encapsulation	organic material	carbon black	1333-86-4	0.120	0.23		2303	
	plastics	epoxy resin	-	2.043	3.92		39150	
solderballs	inorganic material	silicondioxide	60676-86-0	21.877	41.91	46.06	419132	460585
	non noble metal	copper	7440-50-8	0.062	0.12		1186	
	noble metal	silver	7440-22-4	0.371	0.71		7117	
*deviation	< 10%	tin	7440-31-5	11.949	22.89	23.72	228919	237222
		Sum in total:					100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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